

### General Specifications

<b>Resistive Element</b>	Thick film
<b>Substrate</b>	Beryllium oxide ceramic
<b>Cover</b>	Alumina Ceramic
<b>Mounting Flange</b>	Copper, Nickel plated per QQ-N-290
<b>Lead(s):</b>	99.99% pure silver (.006" thick)

### Features:

- DC –See Chart
- 100 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- Welded Silver Leads
- 100% Tested

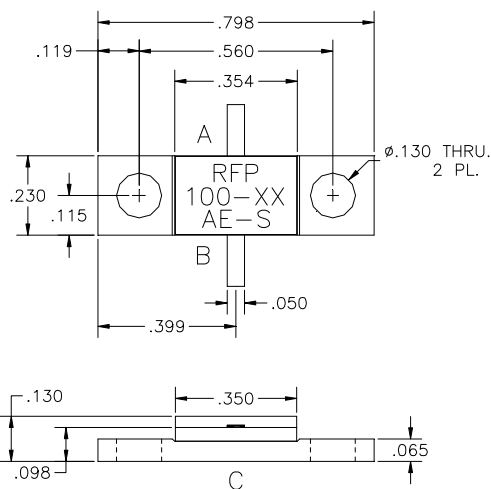
### Electrical Specifications

<b>Attenuation Range:</b>	1, 2, 3, 4, 5, 6, 9, 10, 20, 22 or 30 dB
<b>Frequency Range;</b>	DC – See Chart
<b>Power:</b>	100 Watts
<b>VSWR</b>	See Chart

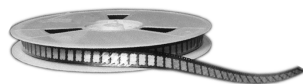
**Note:** Tolerance is  $\pm 0.010"$ , unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. Operating temperature is  $-55^{\circ}\text{C}$  to  $150^{\circ}\text{C}$  (see chart for derating temperatures). All dimensions in inches.

**Specifications subject to change with out notice.**

### Outline Drawing



100-XXAE-S (097) Rev C





## Typical Performance:

SPECIFICATION CHART							
ATTENUATION	FREQ.	VSWR	VALUE (A-B)	VALUE (A-C)	VALUE (B-C)	TOL.	RFP P/N
1dB ±0.4	DC-1GHZ.	1.45:1	5.8 Ω	435.9Ω	435.9Ω	±4%	RFP-100-1AE-S
2dB ±0.4	DC-1GHZ.	1.40:1	11.4 Ω	220.7Ω	220.7Ω	±4%	RFP-100-2AE-S
3dB ±0.4	DC-1GHZ.	1.35:1	17.0 Ω	150.5Ω	150.5Ω	±4%	RFP-100-3AE-S
4dB ±0.3	DC-1GHZ.	1.30:1	22.6 Ω	116.3Ω	116.3Ω	±4%	RFP-100-4AE-S
5dB ±0.3	DC-1GHZ.	1.25:1	28.0 Ω	96.0 Ω	96.0 Ω	±4%	RFP-100-5AE-S
6dB ±0.3	DC-1GHZ.	1.20:1	32.2 Ω	83.6 Ω	83.6 Ω	±4%	RFP-100-6AE-S
9dB ±0.3	DC-1GHZ.	1.20:1	47.6 Ω	64.4 Ω	64.4 Ω	±4%	RFP-100-9AE-S
10dB ±1.2	DC-2GHZ.	1.25:1	52.0 Ω	61.0 Ω	61.0 Ω	±4%	RFP-100-10AE-S
20dB ±0.5	DC-2.5GHZ.	1.20:1	81.7 Ω	50.9 Ω	50.9 Ω	±4%	RFP-100-20AE-S
22dB ±0.5	DC-1GHZ.	1.20:1	85.3 Ω	50.6 Ω	50.6 Ω	±4%	RFP-100-22AE-S
30dB ±2.0	DC-2GHZ.	1.20:1	92.5 Ω	49.6 Ω	49.6 Ω	±4%	RFP-100-30AE-S

## Power De-rating:

## Mounting Footprint and Procedure:

POWER DERATING

P.C.B. SOLDER INTERFACE TEMPERATURE-°C

SUGGESTED STRESS RELIEF METHODS      NOT RECOMMENDED APPLICATION

SCALE: NONE      SCALE: NONE

SUGGESTED MOUNTING PROCEDURES:

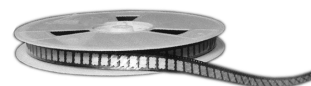
1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING APPROPRIATE SOLDER WITH A CONTROLLED TEMPERATURE IRON.

\*\* FOR MORE DETAILS CONTACT FACTORY \*\*

100-XXAE-S (097) Rev C

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